

### **AO4410**

# N-Channel Enhancement Mode Field Effect Transistor

## **General Description**

The AO4410 uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, shoot-through immunity, body diode characteristics and ultra-low gate resistance. This device is ideally suited for use as a low side switch in Notebook CPU core power conversion. Standard product AO4410 is Pb-free (meets ROHS & Sony 259 specifications). AO4410L is a Green Product ordering option. AO4410 and AO4410L are electrically identical.

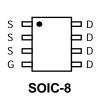
#### **Features**

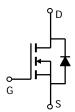
$$V_{DS}(V) = 30V$$

$$I_D = 18A$$
  $(V_{GS} = 10V)$ 

$$R_{DS(ON)}$$
 < 5.5m $\Omega$  ( $V_{GS}$  = 10V)

$$R_{DS(ON)} < 6.2 m\Omega (V_{GS} = 4.5 V)$$





Absolute Maximum Ratings T <sub>A</sub> =25°C unless otherwise noted								
Parameter		Symbol	Maximum	Units				
Drain-Source Voltage		$V_{DS}$	30	V				
Gate-Source Voltage		$V_{GS}$	±12	V				
Continuous Drain	T <sub>A</sub> =25°C		18					
Current <sup>A</sup>	T <sub>A</sub> =70°C	I <sub>D</sub>	15	Α				
Pulsed Drain Current <sup>B</sup>		I <sub>DM</sub>	80					
	T <sub>A</sub> =25°C	Ь	3	W				
Power Dissipation	T <sub>A</sub> =70°C	$-P_{D}$	2.1	]				
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	°C				

Thermal Characteristics								
Parameter	Symbol	Тур	Max	Units				
Maximum Junction-to-Ambient <sup>A</sup>	t ≤ 10s	$ R_{\theta JA}$	31	40	°C/W			
Maximum Junction-to-Ambient <sup>A</sup>	Steady-State	Γ <sub>θ</sub> JA	59	75	°C/W			
Maximum Junction-to-Lead <sup>C</sup>	Steady-State	$R_{ heta JL}$	16	24	°C/W			



#### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
STATIC F	PARAMETERS	•	·		•		
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V			0.005	1	
			T <sub>J</sub> =55°C			5	μΑ
I <sub>GSS</sub>	Gate-Body leakage current	$V_{DS}$ =0V, $V_{GS}$ = ±12V				100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ $I_{D}=250\mu A$		8.0	1.1	1.5	V
$I_{D(ON)}$	On state drain current	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =5V		80			Α
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =18A			4.7	5.5	mΩ
			T <sub>J</sub> =125°C		6.4	7.4	
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A			5.2	6.2	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =18A			102		S
$V_{SD}$	Diode Forward Voltage	I <sub>S</sub> =1A,V <sub>GS</sub> =0V			0.64	1	V
Is	Maximum Body-Diode Continuous Current					4.5	Α
DYNAMIC	PARAMETERS						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz			9130	10500	pF
C <sub>oss</sub>	Output Capacitance				625		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			387		pF	
$\overline{R_g}$	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1		0.4	0.5	Ω	
SWITCHI	NG PARAMETERS						
Q <sub>g</sub> (4.5V)	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =18A			72.4	85	nC
$Q_{gs}$	Gate Source Charge				13.4		nC
$Q_{gd}$	Gate Drain Charge				16.8		nC
t <sub>D(on)</sub>	Turn-On DelayTime				11	15	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS}$ =10V, $V_{DS}$ =15V, $R_L$ =0.83 $\Omega$ , $R_{GEN}$ =3 $\Omega$			7	11	ns
$t_{D(off)}$	Turn-Off DelayTime				99	135	ns
t <sub>f</sub>	Turn-Off Fall Time				13	19.5	ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =18A, dI/dt=100A/μ		33	40	ns	
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =18A, dI/dt=100A/μ		22.2	30	nC	

A: The value of  $R_{\theta JA}$  is measured with the device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$ =25°C. The value in any given application depends on the user's specific board design. The current rating is based on the  $\bowtie$  10s thermal resistance rating. B: Repetitive rating, pulse width limited by junction temperature.

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C. The  $R_{\theta JA}$  is the sum of the thermal impedence from junction to lead  $R_{\theta JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using  $80\mu s$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in  $^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A$ =25°C. The SOA curve provides a single pulse rating.